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Docket No.
03226.111001;P6259

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Senter

Name of Applicant: SUN MICROSYSTEMS, INC.
Address of Applicant: 901 San Antonio Road, MS-PAL01-521
Palo Alto, California 94303

Title: **SOLID ASSEMBLY OF FLIP-CHIP PACKAGE ATTACHED TO
HEAT REMOVAL DEVICE AND METHOD OF
MANUFACTURING SAME**

Serial No., if Any: 10/085,183
Filed: February 27, 2002

TO THE ASSISTANT COMMISSIONER FOR PATENTS

The Assistant Commissioner for Patents
Washington, D.C. 20231

Honorable Sir:

I hereby appoint:

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as principal attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

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Dat d:

March 26, 2002

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10-2800 MAIL ROOM

TRANSMITTAL LETTER

(General - Patent Pending)

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In Application Of: Wen-Chun ZHENG et al.

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TC 2800 MAIL ROOM

Serial No.

10/085,183

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Examiner

Group Art Unit

2815

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METHOD OF MANUFACTURING SAME**

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is:

Power of Attorney, 1 page

in the above identified application.

☒ No additional fee is required.☐ A check in the amount of _____ is attached.☒ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. **50-0591**
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Dated: 5/16/02

Signature

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20231.



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Tawana L. Garcia

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